

Filename: PMP8727RevA - BoM.xls

Date: 11/11/2013

## PMP8727RevA - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C20	10uF	Capacitor, Ceramic, 6.3V, X7R, 10%	0805	Std	Std
1	C21	22pF	Capacitor, Ceramic, 50V, C0G, 5%	0603	Std	Std
1	C23	4.7uF	Capacitor, Ceramic, 6.3V, X7R, 10%	0805	Std	Std
7	J20, J21, J22, J23, J24, J25, J26	PEC02SAAN	Header, Male 2-pin, 100mil spacing	0.100 inch x 2	PEC02SAAN	Sullins
1	JP20	PEC03SAAN	Header, 3 pin, 100mil spacing, (36-pin strip)	0.100 x 3	PEC03SAAN	Sullins
1	L20	2.2uH	Inductor, SMT, 140mOhm, 0.7A, 30%	3.3 x 3.3 x 1.0 mm	744030002	Wuerth
1	R101	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R20, R21	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R22, R23	1.00M	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	U20	TPS62067	IC, Step-Down Converter, 3MHz, 1.6A	SON-8	TPS62067DSG	Texas Instruments

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